

# MC14174B

## Hex Type D Flip-Flop

The MC14174B hex type D flip-flop is constructed with MOS P-channel and N-channel enhancement mode devices in a single monolithic structure. Data on the D inputs which meets the setup time requirements is transferred to the Q outputs on the positive edge of the clock pulse. All six flip-flops share common clock and reset inputs. The reset is active low, and independent of the clock.

- Static Operation
- All Inputs and Outputs Buffered
- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low-Power TTL Loads or One Low-Power Schottky TTL Load over the Rated Temperature Range
- Functional Equivalent to TTL 74174

### MAXIMUM RATINGS (Voltages Referenced to $V_{SS}$ ) (Note 2.)

Symbol	Parameter	Value	Unit
$V_{DD}$	DC Supply Voltage Range	-0.5 to +18.0	V
$V_{in}, V_{out}$	Input or Output Voltage Range (DC or Transient)	-0.5 to $V_{DD} + 0.5$	V
$I_{in}, I_{out}$	Input or Output Current (DC or Transient) per Pin	$\pm 10$	mA
$P_D$	Power Dissipation, per Package (Note 3.)	500	mW
$T_A$	Ambient Temperature Range	-55 to +125	$^{\circ}C$
$T_{stg}$	Storage Temperature Range	-65 to +150	$^{\circ}C$
$T_L$	Lead Temperature (8-Second Soldering)	260	$^{\circ}C$

2. Maximum Ratings are those values beyond which damage to the device may occur.

3. Temperature Derating:  
Plastic "P and D/DW" Packages: - 7.0 mW/ $^{\circ}C$  From 65 $^{\circ}C$  To 125 $^{\circ}C$

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range  $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$ .

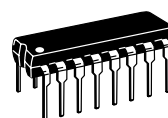
Unused inputs must always be tied to an appropriate logic voltage level (e.g., either  $V_{SS}$  or  $V_{DD}$ ). Unused outputs must be left open.



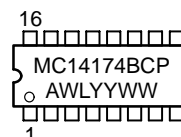
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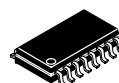
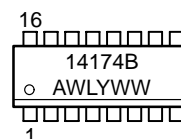
### MARKING DIAGRAMS



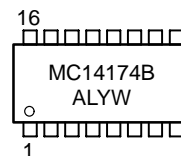
PDIP-16  
P SUFFIX  
CASE 648



SOIC-16  
D SUFFIX  
CASE 751B



SOEIAJ-16  
F SUFFIX  
CASE 966



A = Assembly Location  
WL, L = Wafer Lot  
YY, Y = Year  
WW, W = Work Week

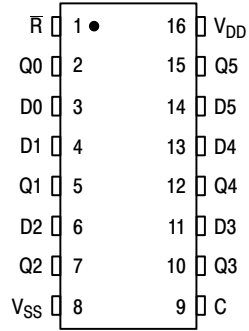
### ORDERING INFORMATION

Device	Package	Shipping
MC14174BCP	PDIP-16	2000/Box
MC14174BD	SOIC-16	48/Rail
MC14174BDR2	SOIC-16	2500/Tape & Reel
MC14174BF	SOEIAJ-16	See Note 1.
MC14174BFEL	SOEIAJ-16	See Note 1.

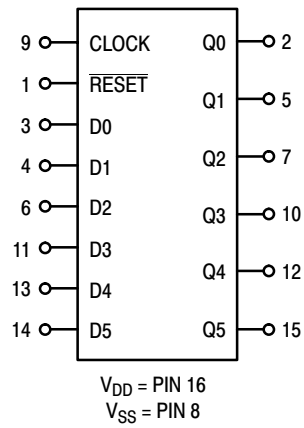
1. For ordering information on the EIAJ version of the SOIC packages, please contact your local ON Semiconductor representative.

# MC14174B

## PIN ASSIGNMENT



## BLOCK DIAGRAM



## TRUTH TABLE (Positive Logic)

Inputs			Output
Clock	Data	Reset	Q
	0	1	0
	1	1	1
	X	1	Q
X	X	0	0

No  
Change

X = Don't Care

# MC14174B

## ELECTRICAL CHARACTERISTICS (Voltages Referenced to $V_{SS}$ )

Characteristic	Symbol	$V_{DD}$ Vdc	-55°C		25°C			125°C		Unit	
			Min	Max	Min	Typ (4.)	Max	Min	Max		
Output Voltage $V_{in} = V_{DD}$ or 0	"0" Level $V_{OL}$	5.0	—	0.05	—	0	0.05	—	0.05	Vdc	
		10	—	0.05	—	0	0.05	—	0.05		
15		—	0.05	—	0	0.05	—	0.05			
$V_{in} = 0$ or $V_{DD}$	"1" Level $V_{OH}$	5.0	4.95	—	4.95	5.0	—	4.95	—	Vdc	
		10	9.95	—	9.95	10	—	9.95	—		
		15	14.95	—	14.95	15	—	14.95	—		
Input Voltage ( $V_O = 4.5$ or $0.5$ Vdc) ( $V_O = 9.0$ or $1.0$ Vdc) ( $V_O = 13.5$ or $1.5$ Vdc)	"0" Level $V_{IL}$	5.0	—	1.5	—	2.25	1.5	—	1.5	Vdc	
		10	—	3.0	—	4.50	3.0	—	3.0		
		15	—	4.0	—	6.75	4.0	—	4.0		
	"1" Level ( $V_O = 0.5$ or $4.5$ Vdc) ( $V_O = 1.0$ or $9.0$ Vdc) ( $V_O = 1.5$ or $13.5$ Vdc)	$V_{IH}$	5.0	3.5	—	3.5	2.75	—	3.5	—	Vdc
			10	7.0	—	7.0	5.50	—	7.0	—	
			15	11	—	11	8.25	—	11	—	
Output Drive Current ( $V_{OH} = 2.5$ Vdc) ( $V_{OH} = 4.6$ Vdc) ( $V_{OH} = 9.5$ Vdc) ( $V_{OH} = 13.5$ Vdc)	Source $I_{OH}$	5.0	-3.0	—	-2.4	-4.2	—	-1.7	—	mAdc	
		5.0	-0.64	—	-0.51	-0.88	—	-0.36	—		
		10	-1.6	—	-1.3	-2.25	—	-0.9	—		
		15	-4.2	—	-3.4	-8.8	—	-2.4	—		
	Sink ( $V_{OL} = 0.4$ Vdc) ( $V_{OL} = 0.5$ Vdc) ( $V_{OL} = 1.5$ Vdc)	$I_{OL}$	5.0	0.64	—	0.51	0.88	—	0.36	—	mAdc
			10	1.6	—	1.3	2.25	—	0.9	—	
15	4.2	—	3.4	8.8	—	2.4	—	—			
Input Current	$I_{in}$	15	—	$\pm 0.1$	—	$\pm 0.00001$	$\pm 0.1$	—	$\pm 1.0$	$\mu$ Adc	
Input Capacitance ( $V_{in} = 0$ )	$C_{in}$	—	—	—	—	5.0	7.5	—	—	pF	
Quiescent Current (Per Package)	$I_{DD}$	5.0	—	5.0	—	0.005	5.0	—	150	$\mu$ Adc	
		10	—	10	—	0.010	10	—	300		
		15	—	20	—	0.015	20	—	600		
Total Supply Current (5.) (6.) (Dynamic plus Quiescent, Per Package) ( $C_L = 50$ pF on all outputs, all buffers switching)	$I_T$	5.0	$I_T = (1.1 \mu\text{A/kHz}) f + I_{DD}$							$\mu$ Adc	
		10	$I_T = (2.3 \mu\text{A/kHz}) f + I_{DD}$								
		15	$I_T = (3.7 \mu\text{A/kHz}) f + I_{DD}$								

4. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

5. The formulas given are for the typical characteristics only at 25°C.

6. To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

where:  $I_T$  is in  $\mu\text{A}$  (per package),  $C_L$  in pF,  $V = (V_{DD} - V_{SS})$  in volts,  $f$  in kHz is input frequency, and  $k = 0.003$ .

# MC14174B

## SWITCHING CHARACTERISTICS (7.) ( $C_L = 50 \text{ pF}$ , $T_A = 25^\circ\text{C}$ )

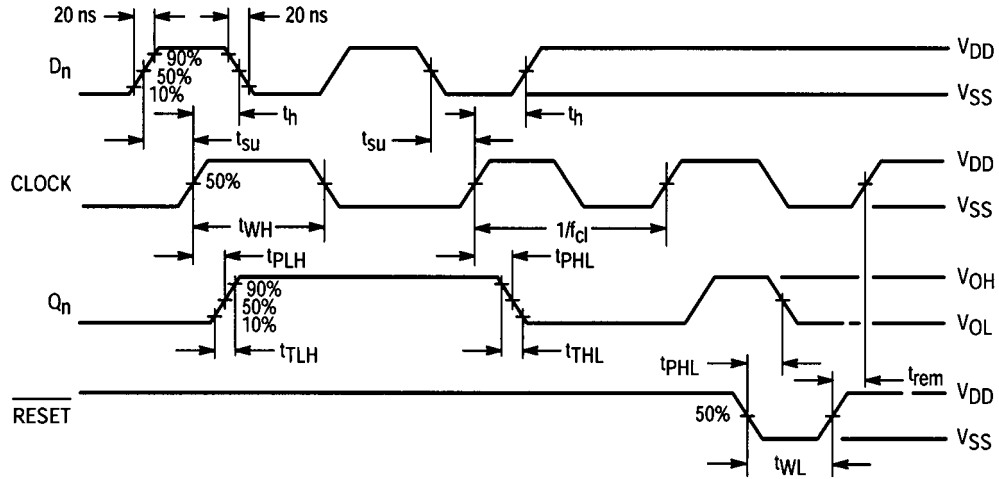
Characteristic	Symbol	$V_{DD}$ Vdc	All Types			Unit
			Min	Typ (8.)	Max	
Output Rise and Fall Time $t_{TLH}$ , $t_{THL} = (1.35 \text{ ns/pF}) C_L + 32 \text{ ns}$ $t_{TLH}$ , $t_{THL} = (0.6 \text{ ns/pF}) C_L + 20 \text{ ns}$ $t_{TLH}$ , $t_{THL} = (0.4 \text{ ns/pF}) C_L + 20 \text{ ns}$	$t_{TLH}$ , $t_{THL}$	5.0 10 15	— — —	100 50 40	200 100 80	ns
Propagation Delay Time — Clock to Q $t_{PLH}$ , $t_{PHL} = (0.9 \text{ ns/pF}) C_L + 165 \text{ ns}$ $t_{PLH}$ , $t_{PHL} = (0.36 \text{ ns/pF}) C_L + 64 \text{ ns}$ $t_{PLH}$ , $t_{PHL} = (0.26 \text{ ns/pF}) C_L + 52 \text{ ns}$	$t_{PLH}$ , $t_{PHL}$	5.0 10 15	— — —	210 85 65	400 160 120	ns
Propagation Delay Time — Reset to Q $t_{PHL} = (0.9 \text{ ns/pF}) C_L + 205 \text{ ns}$ $t_{PHL} = (0.36 \text{ ns/pF}) C_L + 79 \text{ ns}$ $t_{PHL} = (0.26 \text{ ns/pF}) C_L + 62 \text{ ns}$	$t_{PHL}$	5.0 10 15	— — —	250 100 75	500 200 150	ns
Clock Pulse Width	$t_{WH}$	5.0 10 15	150 90 70	75 45 35	— — —	ns
Reset Pulse Width	$t_{WL}$	5.0 10 15	200 100 80	100 50 40	— — —	ns
Clock Pulse Frequency	$f_{cl}$	5.0 10 15	— — —	7.0 12 15.5	2.0 5.0 6.5	mHz
Clock Pulse Rise and Fall Time	$t_{TLH}$ , $t_{THL}$	5.0 10 15	— — —	— — —	15 5.0 4.0	$\mu\text{s}$
Data Setup Time	$t_{su}$	5.0 10 15	40 20 15	20 10 0	— — —	ns
Data Hold Time	$t_h$	5.0 10 15	80 40 30	40 20 15	— — —	ns
Reset Removal Time	$t_{rem}$	5.0 10 15	250 100 80	125 50 40	— — —	ns

7. The formulas given are for the typical characteristics only at 25°C.

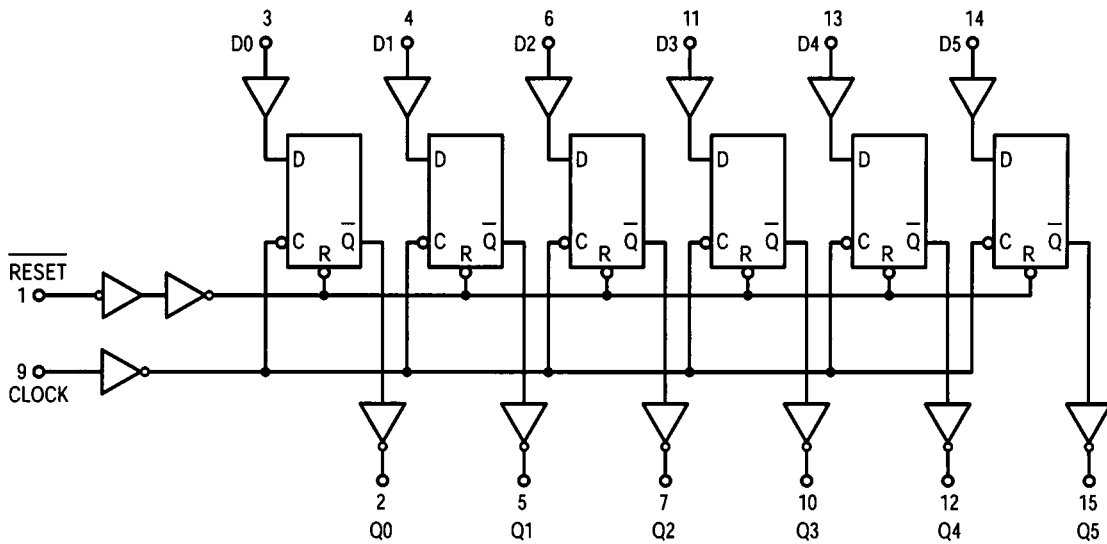
8. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

# MC14174B

## TIMING DIAGRAM



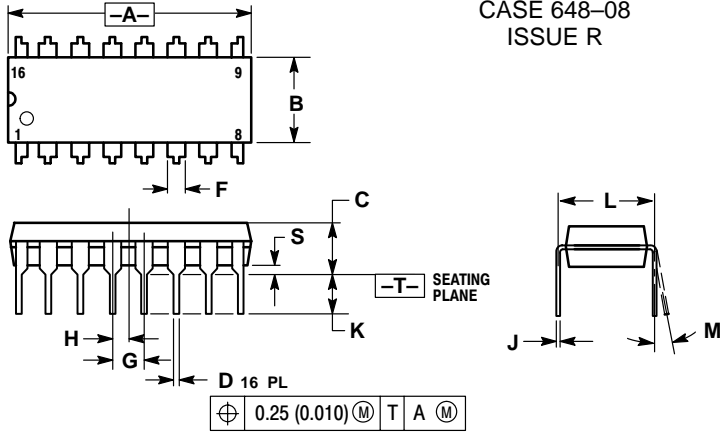
## FUNCTIONAL BLOCK DIAGRAM



# MC14174B

## PACKAGE DIMENSIONS

### PDIP-16 P SUFFIX PLASTIC DIP PACKAGE CASE 648-08 ISSUE R

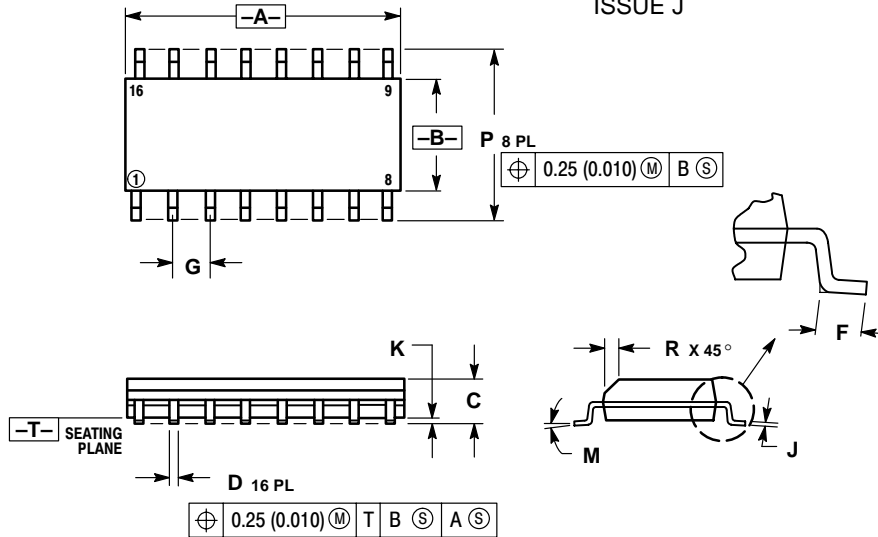


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

### SOIC-16 D SUFFIX PLASTIC SOIC PACKAGE CASE 751B-05 ISSUE J



NOTES:

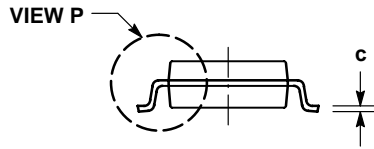
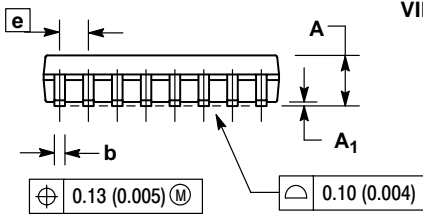
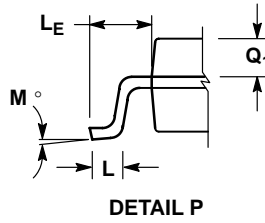
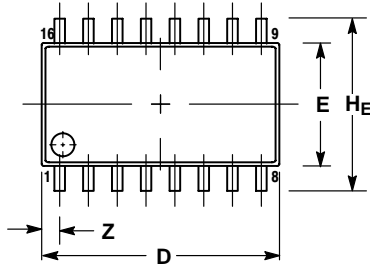
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

# MC14174B

## PACKAGE DIMENSIONS


### SOEIAJ-16 F SUFFIX PLASTIC EIAJ SOIC PACKAGE CASE 966-01 ISSUE O



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0°	10°	0°	10°
Q <sub>1</sub>	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031

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